

Major Ratings and Characteristics

$I_{F(AV)}$	3.0 A
V_{RRM}	20 V to 100 V
I_{FSM}	100 A
V_F	0.55 V , 0.70 V , 0.85V
$T_J \text{ max.}$	150 °C



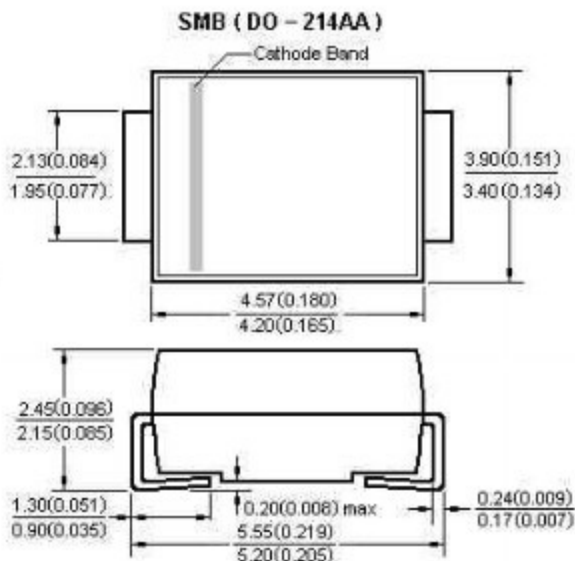
SMB (DO - 214AA)

Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Data

- Case: JEDEC DO-214AA molded plastic body over passivated chip
- Terminals: Solder plated, solderable per



Dimensions in millimeters and (inches)